PRESS RELEASE

FOR IMMEDIATE RELEASE

Buc, France, May 2009, 4th – Successful renewal of 3D PLUS ISO 9001/2000 Certification until November 2010

3D Plus is very pleased to announce the Successful Renewal of its ISO 9001:2000 Certification for the Design, Manufacturing, test and sales of microelectronics modules.

3D Plus SA and 3D Plus USA, Inc. have been certified by Lloyd's Register Quality Assurance as being in full compliance with the requirements of the ISO9001:2000 Quality System.

ISO9001 is an International Standard for quality management systems. This standard contains requirements that aim to assure the quality of products and enhance customer satisfaction. It gives also our customers and suppliers a set of guidelines that is accepted worldwide and that can be followed to achieve a definable level of quality.

"The Successful Renewal of our ISO 9001:2000 Certification is the success of 3D Plus personnel and results from its intense involvement for maintaining and improving our quality system. Also, It confirms that 3D Plus's systems for accepting orders up to products delivery to its customers are quality controlled and should produce consistent results. It comes in addition with 3D stacking technical certifications. These high quality standards ensure the development and the manufacturing of high quality and high reliability products for very demanding markets such as Medical and Aerospace." said Pierre-Eric Berthet, 3D Plus Director of Sales and Marketing.

3D Plus products fly in numerous satellite programs for all major space agencies worldwide. Most of the Space missions launched recently, or, to be launched soon embeds 3D Plus Modules. Current customers' portfolio includes the major Aerospace prime contractors and equipment manufacturers spread over more than 30 countries.

About 3D PLUS company:

Founded in 1995 as a spin-off of Thales, 3D Plus has become a worldwide actor for the advanced high density 3D package and die stacking technology meeting the demand for high reliability, extreme performance and very small size electronics.

Its portfolio of patented and very advanced stacking technologies starts with Package scale upward to die-size and wafer-level packaging techniques and provides leading edge, highly integrated and rugged modules embedding Active, Passive, Opto-electronics and MEMS/MOEMS components.

With a broad range of catalogue products including memory modules, camera heads, power converters and computer modules, with its very miniaturized System-In-Package solutions and by Licensing its technologies, 3D PLUS meets the requirements of high technology industries in industrial, telecom., computer/blade server, military, avionics, medical and space markets.

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